Honeywell's Docket No. H0002908 DIV (4960) Practitioner's Docket No. 100665.0044US2





PATENT

IN THE UNITED STATES PARENTAL TRADEMARK OFFICE

In re application of: Jesse PEDIGO

Group No.: 1732

Application No.:

10/026,337

Examiner:

Not Yet Assigned

Filed:

December 20,2001

For:

Scavenging Method

Box DD Assistant Commissioner for Patents Washington, D.C. 20231

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
WITHIN THREE MONTHS OF FILING OR
BEFORE MAILING OF FIRST OFFICE ACTION (37 C.F.R. 1.97(b))

IDENTIFICATION OF TIME OF FILING THE ACCOMPANYING INFORMATION DISCLOSURE STATEMENT

The information disclosure statement submitted herewith is being filed within three months of the filing date of the application or date of entry into the national stage of an international application or before the mailing date of a first Office action on the merits, whichever event occurs last. 37 C.F.R. 1.97(b).

By:

Respectfully submitted,

Date: June 4, 2002

David J. Zoetewey Reg. No. 45,258

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CERTIFICATE OF MAILING (37 C.F.R. 1.8(a))

I hereby certify that, on the date shown below, this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C.

Kristin I Azcons

Date: June 4, 2002

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IN THE UNITED STATE PATENT AND TRADEMARK OFFICE WASHINGTON, D.C. 20231

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INFORMATION DISCLOSURE STATEMENT

Box DD Assistant Commissioner of Patents Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure imposed by 37 C.F.R. § 1.56 to inform the United States Patent and Trademark Office of all references coming to the attention of the Applicant(s) or attorneys or agents for Applicant(s) which are or may be material to the examination of the subject application, attorneys for the Applicant(s) hereby invite the Examiner's attention to the references listed in the accompanying PTO Form 1449 entitled "List of References Cited".

This submission is understood to complement the results of the Examiner's own independent search. The submission of this Disclosure Statement should not be construed as a representation that a search was made, or that the cited items are inclusive of all relevant and material citations that may be available publicly.

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Applicant(s) respectfully request that the Examiner review the foregoing references, as set forth in the Form PTO-1449, and that they be made of record in the file history of the above-captioned application.

Respectfully submitted,

Rutan & Tucker, LLP

Dated: June 4, 2002

By:______ David J. Zoetewey

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LIST OF R	EFERENCES CITED BY A	PPLICANT/	JUN , , SE	APPLICANY		10/026337		
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U.S. PATEN	T DOCUMENTS			,		V, 5%		
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME		CLASS	SUBOLASS	FILIN IF APPR	O DATE
	4,945,313	07/31/90	1	Synchronous Demodulator Having Automatically Tuned Band-Pass Filter		349	06/05/89	
	5,117,069	05/26/92	Circuit Board Fabrication Method of Filling Conductive Material into Through Holes of Printed Wiring Boards Methods and Apparatus for Making Grids from Fibers Screen Printing Apparatus for Filling Though- Holes in Circuit Board With Paste Method for Filling Vias in Ceramic Substrates with Composite Metallic Paste System for Fabricating Conductive Epoxy Grid Array Semiconductor Packages Multi-Layer Circuit Having a Via Matrix Interlayer Connection Method for Filling Holes in Printed Wiring Boards Method of Making Films and Coatings Having Anisotropic Conductive Pathways Therein		174	261 09/28/90		3/90
	5,133,120	07/28/92			29	852	03/15/91	
	5,277,854	01/11/94			264	86	06/06/91	
A	5,332,439	07/26/94			118	213	08/18/92	
	5,707,575	01/13/98			264	104	07/28/94	
	5,744,171	04/28/98			425	110	05/12/97	
·	5,753,976	05/19/98			257	774	06/14/96	
	6,015,520	01/18/00			264	104	05/15/97	
	6,149,857	11/21/00			264	429	12/22/98	
	6,184,133	02/06/01		Method of Forming an Assembly Board With Insulator Filled Through Holes		667	02/18/00	
	6,261,501	07/17/01	Resin Sealing Method for a Semiconductor Device		264	272.15	01/22/99	
FOREIGN PA	ATENT DOCUMENTS	'						
	DOCUMENT NUMBER	DATE		COUNTRY		SUBCLASS	TRANSLATION	
	DOCUMENT NUMBER	UNIC					YE8	NO
	WO 00/13474							
OTHER REF	ERENCES (Including Author, Title	e, Date, Pertinent	Pages, Etc.)					
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.